Home Wafer-maker

www.wafee.sk

www.oblatkovac.sk

HOME WAFER-MAKER

CONTENTS

INSTRUCTION MANUAL

Dear customer!

Thank you for deciding to buy our Wafee wafer-maker for making your own homemade wafers.

We are certain that it will meet your expectations and that you will be satisfied.

Before using the wafer-maker for the first time, please familiarize yourself with the device by carefully reading this instruction manual.

Basic safety instructions

o This electrical appliance is intended for private use only.

o Never disassemble or repair the wafer-maker yourself. Improper handling and repairs create a risk for the user and at the same time void any warranty on the device.

o Before using the appliance for the first time, make sure that the mains voltage indicated on the appliance corresponds to the mains voltage in your home.

o If the power cord is damaged, contact the manufacturer and discontinue use.

o Pull the mains plug out of the socket (always pull the plug, never the cable):

- if a failure occurs,
- if the appliance will not be used for a long time,
- before each cleaning.

o Do not over-stretch the power cord, otherwise it may be damaged.

o Do not run the power cord over sharp edges, protect it from heat and fire (stove, open flame, ...) and moisture (splashing water, rain, ..).

o Never use the power cord to carry the device.

o Children are not aware of the dangers involved in handling the appliance, so pay attention to their safety. Children should be supervised to ensure that they do not play with the appliance.

o This appliance is not intended for use by persons (including children) with reduced physical, sensory or mental capabilities, or lack of experience, unless they have been given supervision or instruction with regards to its use by a responsible individual.

o Allow the appliance to cool down completely before cleaning and storing it.

o This appliance is intended exclusively for baking particular types of wafers.

WARNING !!!

During operation, the entire appliance heats up to a high temperature and the baking trays can reach up to 210 ° C. There is a risk of burns. Therefore, hold the device only by the handle during operation!

Get to know your Wafee wafer-maker – description

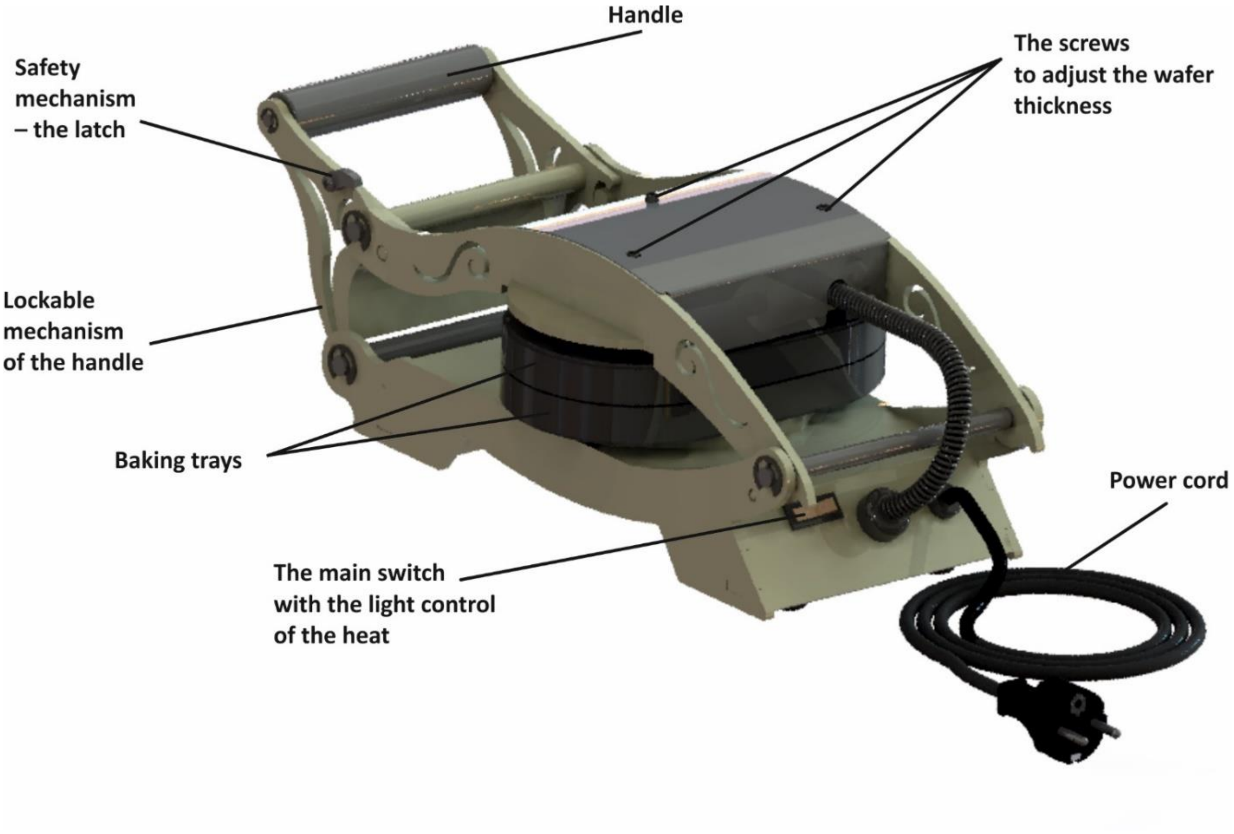
Technical parameters:

Appliance dimensions: 430 x 200 x 145 mm

Weight: 10 kg

220 - 240 V ~ 50 Hz ~ 750 W

Mold dimensions: 200 x 120 mm



WAFEE WAFER – MAKER OPERATION INSTRUCTIONS

(1) Begin operation and first baking

If the device is stored in a room below 5 ° C, it must be allowed to reach room temperature (min. 12 hours) before being plugged in and turned on. Otherwise there is a risk of short-circuiting and seriously damaging the device , which would not be covered under the warranty! ! !

o Before using the appliance for the first time and connecting it to the mains, remove all packaging.

o Always carry the device by grasping the locked handle secured with a latch. Make sure that the power cord is rolled up and not hanging loose.

o Place the device on a flat and non-slip surface.

o Insert the mains plug into the socket.

o Before switching on the appliance, check the thermostat setting on the bottom of the appliance. The manufacturer recommends setting the operating temperature within the marked range - see. “Setting the temperature of the baking trays” (p.6).

o Turn the main switch on the device to position "I". The indicator light on the switch will light up to indicate that the hotplates have begun warming up to the set temperature.

o Before you start baking wafers, the wafer-maker's baking surfaces must first be warmed up to the set temperature.

o It takes approx. 15 min to heat the baking trays to the required (set) temperature. - Close the wafer-maker and wait until the light goes out.

WARNING! The appliance is now warming up.

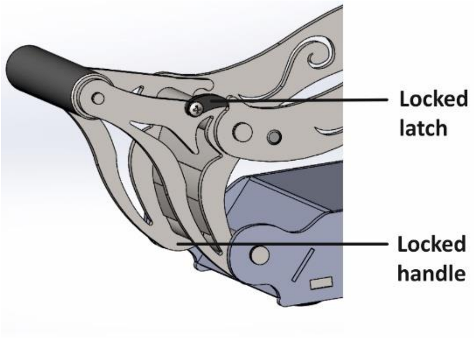
The baking trays and the surface of the appliance are now hot!

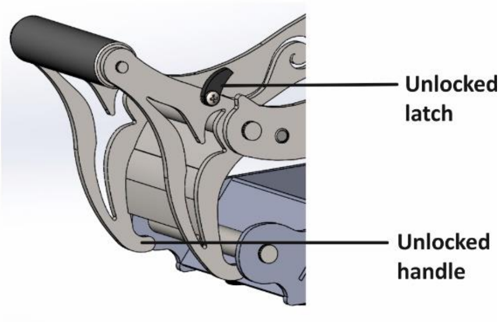
Do not touch them, there is a risk of burns!

o Hold the device only by the handle during operation.

o When the baking trays are sufficiently warm, the light on the main switch goes out. When the light goes out, unlock the latch, unlock (loosen) the handle, and open the wafer-maker.

o The wafer-maker is now ready to bake its first wafers.





The first baking

o DO NOT WIPE the baking trays before the first baking! During production, the baking trays were treated with beeswax.

o Now you can start baking.

o All impurities from the trays will come off and stick to approx. the first 10 baked wafers, therefore:

THE FIRST 10 BAKED WAFERS MUST BE DISCARDED – DO NOT EAT!

Manufacturer's recommendation::

FOR THE VERY FIRST BAKING, the baking trays must be "baked out". We recommend starting with baking salty wafers. The batter for salty wafers does not contain sugar, which caramelizes, so during the first baking it can cause the wafers to stick to the baking trays. By baking a salty batter, the trays are "baked out" and are then ready for further baking. The first 10 baked wafers must be discarded - DO NOT EAT!

(2) Adjusting the thickness of the wafer

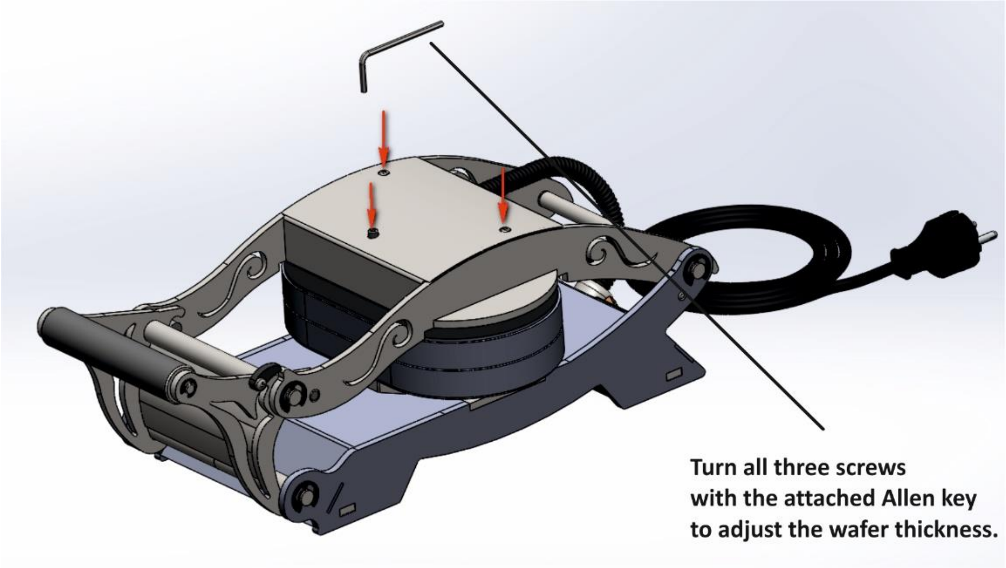
o The wafer is set by the manufacturer to a certain wafer thickness, which you can change.

o This is done by using the 3 screws on the top of the wafer-maker. Using the included tool (3), you can easily turn the screws to change the thickness of the wafer.

o To keep the same thickness of the wafer over the entire surface, all three screws must always be turned in the same way.

o Turning the screw by one turn (360 °) means the thickness of the wafer will be changed by 1 mm, so be careful when adjusting the thickness and adjust only by turning slightly, max. after 1/4 turn always in the same direction.

o Turning the screws to the right decreases the thickness of the wafer, while turning the screws to the left increases the thickness of the wafer.



Manufacturer's recommendation::

If one side of the wafer is darker after baking, loosen the screw on this side of the wafer-maker by turning it to the left (turning approx. 5-10 min., See pictures below).

Rotating 5 min.

Rotating 10 min.

Rotating 15 min. (¼ turn)

If you are unsure of the correct setting of the screws – gradually turn all three screws about ½ turn to the right until the baking trays are completely closed and the screws can no longer be turned (note that the wafer-maker cannot be opened in this state). Continue by gradually turning the screws to the left three times - ½ turn each time, so in essence you have turned each screw one and a half turns.

(3) Setting the temperature of the baking trays

o On the bottom of the appliance there is a control dial for the thermostat with a scale of 1 - 8 according to the operating temperature of the baking molds:

1 – minimum temperature, approx. 150°C (+ / - 10°C),

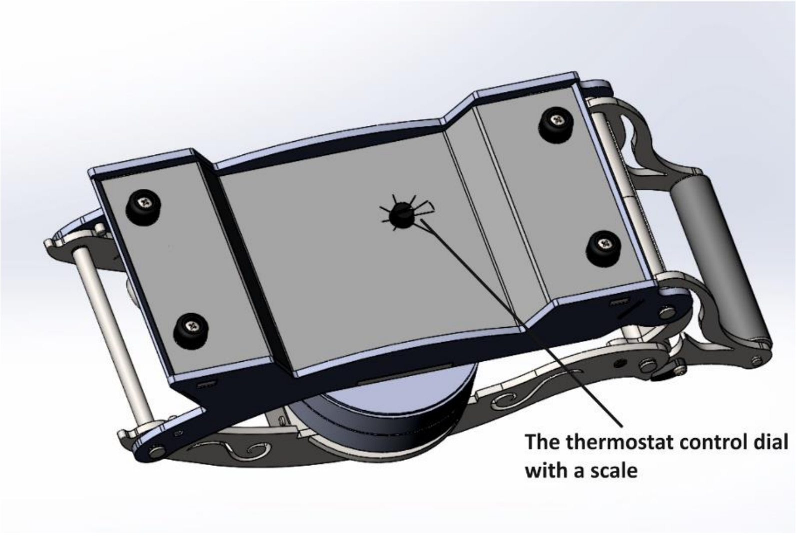
8 – maximum temperature, approx. 210 ° C (+ / - 10 ° C).

o Set the temperature only when there is no batter or baked wafers in the wafer-maker.

o Ensure that the wafer-maker will not open by using the latch.

o With one hand, lift the wafer-maker by the locked and latched handle to reach the thermostat control dial located at the bottom of the appliance. With the other hand, turn the knob to change the temperature setting.

- Note. Since the device has solid trays that have a thermal inertia, the temperature change will not take effect until after a certain time (approx. 3-5 minutes), so be patient when regulating the temperature.



4) Preparing the wafer batter

Manufacturer's recommendation:

During the first baking, we recommend that you begin with recipes already tested on our wafer-maker - see. page 17.

(5) Pouring the batter into the wafer-maker and baking

- Using a ladle or spoon, pour the batter onto the lower baking tray.
- After pouring the batter, slowly close the wafer-maker. The weight of the upper plate spreads the batter evenly using this pressure to set the wafer's thickness.
- Baking one wafer takes a few seconds depending on the type of batter (approx. 30 seconds).
- Properly baked wafers have a golden color (slightly darker than the color of the batter).
- When the wafer is baked, carefully remove it from the baking tray and set it aside. The ideal helper for removing baked wafers is the multi-purpose Baking Buddy Baton, or a cutlery knife (round).
- Even if the wafers are brittle, they can still be stacked (one on top of the other) immediately after removing them from the baking tray.
- After removing the wafer, you can pour the next ladle of batter and repeat the whole process.

Manufacturer's recommendation:

Watery batter: after pouring the batter, slowly close the wafer-maker, no need to lock the handle. The weight of the upper plate spreads the batter evenly. After the liquid has evaporated from the batter, the handle usually locks itself.

Thick batter: after pouring the batter, slowly close the wafer-maker and carefully lock the handle to achieve the desired wafer thickness.

(6) Cleaning and care

- Before cleaning, switch off the appliance by turning the main switch to the "0" position and remove the mains plug.
- Let the appliance completely cool down.
- Never wash the appliance under running water!
- Depending on how dirty it is, clean the appliance (EXCEPT the baking trays) with a damp cloth or paper towel - then thoroughly wipe dry.
- NEVER WIPE THE BAKING TRAYS WITH A WET OR DAMP CLOTH!!!

If the trays are very dirty then clean them with a wire brush. After such a cleaning, however, it is necessary to treat the baking surfaces with beeswax to prevent the next wafers from sticking. Once again, be sure not to eat the first baked wafers, but discard them!

Read more:

HOW TO USE BEE WAX CORRECTLY - read CAREFULLY !!!

- Beeswax is used to treat and preserve the baking tray as well as preventing the batter from sticking.

- You only need to treat the baking trays with beeswax once, preferably after each wafer baking session (it also depends on how many wafers you bake and how often).

Before putting the wafer-maker away, it is advisable to place a sheet of greased baking paper between the baking trays, NEVER a paper towel!!!

- If the baking trays are clean and treated, but the wafers still stick together, it is necessary to make adjustments to the wafer batter – DO NOT ADD MORE BEESWAX TO THE TRAY!!!

- Under no circumstances use edible oil, because over time it will have the opposite effect - the wafers will start to stick to the trays and smell.

Guidelines for using beeswax:

1. Let the baking plates warm up - pay attention to safety, there is a risk of burns.
2. Wrap the beeswax in a cotton cloth (or use beeswax wrapped in a linen bag).
3. With the wax prepared in this way, grease the still hot baking surfaces and the edges of the trays - just a small amount, be sure not to let the wax drip off the baking tray.

Note: Improper use of beeswax can damage the product (for example by wax leaking into the electrical components). Such damage to the product is not accepted as a reason for complaint or return.

(7) Storing the wafer-maker

o Store the wafer-maker in a warm (above 5 ° C) and dry place.

o If the appliance is to be stored in a room below 5 ° C, before plugging it in for its next use it must be allowed to reach room temperature (min. 12 hours). Otherwise there is a risk of short-circuiting and causing serious damage to the appliance, which will not be covered by the warranty! ! !

TROUBLESHOOTING

Problem / Cause / Solution

The appliance doesn't work.	The appliance is not connected to the electrical network	Plug the appliance into the electrical socket.
	The appliance is not turned on.	Turn on the appliance by turning the dial to the “I“ position.
	The temperature on the thermostat is too low.	Increase the temperature on the thermostat.
The wafers are too dark.	Baking time is too long.	Shorten the baking time.
	Temperature of the mold is too high.	Lower the temperature on the thermostat.
	Not enough batter.	Increase the amount of batter.
	Incorrect setting of wafer thickness.	Adjust the thickness of the wafer by turning the screw. On the side where the wafer is too dark, increase the thickness of the wafer. (More on page 5)
The wafers are too light.	Baking time is too short.	Increase the baking time.
	Temperature of the mold is too low.	Raise the temperature on the thermostat.
	Too much batter.	Decrease the amount of batter.
	Incorrect setting of wafer thickness.	Adjust the thickness of the wafer by turning the screw. On the side where the wafer is too light, decrease the thickness of the wafer. (More on page 5)

The batter sticks to the trays.	Too much sugar.	Reduce the amount of sugar in the batter.
	Too many additional flavoring ingredients (nuts, dried fruits, etc.).	Reduce the amount of these ingredients in the batter.
	Using unsuitable baking fat.	Use only fats suitable for baking.
	Dirty baking surfaces (during baking, an almost invisible layer can form on the surface of the baking trays, which can cause the batter to stick - especially caramelized sugar).	Clean the baking surfaces (more on page 7)
The batter leaks from the molds	Too much batter.	Decrease the amount of batter.
The wafers crumble.	Not enough flour in the batter.	Increase the amount of flour in the batter.
	Unsuitable type of flour (low gluten content).	Use a different type of flour.
Long time baking wafers.	The batter is too cold and is cooling the baking surfaces.	Before baking allow the batter to sit until it reaches room temperature. Do not use batter directly from the refrigerator.
The baking trays cannot be opened after pouring the batter.	Unsuitable ingredients in the batter that cause it to stick (eg powdered sugar, too much sugar, dried fruit, poor quality cheese ...).	Switch off the appliance and let it cool down completely. Carefully try to open the wafer-maker mechanically – with slight force. Clean the baking trays, p. 7. Reduce the amount of ingredients that are causing the batter to stick.
	Incorrectly set wafer thickness - wafer is too thin.	Increase the thickness of the wafer, p. 5.
	Incorrect temperature setting on the thermostat - temperature is too high.	Reduce the temperature on the thermostat, p. 6.

Warranty conditions

Manufacturer KOVO, Ltd. provides the customer with a two-year warranty on the wafer-maker from the date of purchase.

Exemption from the warranty will occur when damage to the wafer-maker is caused by:

- misuse,
- natural wear and tear,
- unprofessional handling of the device and its parts (unprofessional repairs and opening or disassembling of the device),
- other influences (transport damage, dropping or banging into the device, effects from heat, acids, ...).

Improper handling, repairs and changes to the device will void any product warranty!

The warranty will also be rendered invalid if the device is used commercially.

Be careful not to damage the label with the original serial number.

Note:

If the appliance is to be stored in a room below 5 ° C, before plugging it in for its next use it must be allowed to reach room temperature (min. 12 hours). Otherwise there is a risk of short-circuiting and causing serious damage to the appliance, which will not be covered by the warranty! ! !

Improper use of beeswax can damage the product (for example by wax leaking into the electrical components). Such damage to the product is not accepted as a reason for complaint or return.

Improper handling can damage the thermostat control - the thermostat control dial (knob) on the bottom of the device. Such damage to the product is not subject to complaint or return.

The manufacturer reserves the right to make any construction changes to the design.

Customer service

If your wafer-maker has a defect, contact the manufacturer. Have the wafer-maker repaired and disassembled only by the manufacturer, otherwise it will not be covered by the warranty. Before sending the wafer-maker to the manufacturer, clean it thoroughly. In case of further questions regarding the wafer-maker, please contact us at info@wafee.sk

WARRANTY

Product: **WAFER-MAKER WAFEE**

Type: **OB1**

Manufacturer: **KOVO, s.r.o.**
Družby 77
921 01 Piešťany – Kocurice
Company Registration Number: 31444512
VAT ID: 2020396752

Serial number: ……………………………………………………………………………………

Engraving design: ……………………………………………………………………………

Date: ……………………
Signature and stamp: ……………………………………………

TSU®

TECHNICKÝ SKÚŠOBNÝ ÚSTAV PIEŠŤANY, š.p.
Krajinská cesta 2929/9
921 01 Piešťany, Slovenská republika

SNAS
Reg. No. 009/P-018

CERTIFIKÁT ZHODY
CONFORMITY CERTIFICATE

č./*No.* 141299001

Výrobca *Manufacturer*	**KOVO, s.r.o.** **ul. Družby 77, 921 01 Piešťany, Slovenská republika / *Slovak Republic***
Žiadateľ *Applicant*	**KOVO, s.r.o.** **ul. Družby 77, 921 01 Piešťany, Slovenská republika / *Slovak Republic***
Výrobok *Product*	**OBLÁTKOVAČ** ***Wafer Maker***
Typ *Type*	**OB-1**
Podklad pre vydanie certifikátu *Basis of certificate*	**Záverečný protokol č.: 130500122/1/2014 zo dňa 10.01.2014** ***Final report No.: 130500122/1/2014 of January 10th, 2014***

Týmto certifikátom zhody potvrdzuje, že výrobok spĺňa základné požiadavky na bezpečnosť podľa nasledovných smerníc ES nového prístupu (nariadení vlády Slovenskej republiky) v ich platnom znení:
This conformity certificate confirms the conformity of tested sample with essential safety requirements of the following EC New Approach Directives (Governmental Ordinances of Slovak Republic) as amended:

Smernica o nízkom napätí 2006/95/EC (Nariadenie vlády SR č. 308/2004 Z.z.)
Low Voltage Directive 2006/95/EC (Governmental Ordinance of Slovak Republic No. 308/2004 Coll.)

Európske harmonizované normy aplikované pre stanovenie zhody so základnými bezpečnostnými požiadavkami vyššie uvedených smerníc:

- **STN EN 60335-1:2012**
- **STN EN 60335-2-9:2004 + A1:2005 + A2:2007 + A12:2008 + A13:2011**

European harmonized standards applied for conformity assessment with essential safety requirements of above mentioned directives:

- ***EN 60335-1:2012***
- ***EN 60335-2-9:2003 + A1:2004 + A2:2006 + A12:2007 + A13:2010***

CE označenie môže byť použité iba v prípade, že je posúdená zhoda so všetkými príslušnými smernicami Európskej komisie.
Akékoľvek významné zmeny v zhotovení alebo konštrukcii výrobku, systéme kvality a dodatky k hore uvedeným technickým a právnym predpisom môžu viesť k neplatnosti certifikátu. Zodpovednosť za výrobok zostáva na výrobcovi alebo jeho splnomocnenom zástupcovi.

CE *mark can be used only in the case of conformity assessment according to all relevant Directives of the European Commission.*
Any significant change in product's form or construction, system of quality and supplements to above mentioned technical and legal provisions can result in invalidity of the certificate. Producer or his representative is responsible for the product.

Vydaný dňa: 14.01.2014
Date of issue: January 14th,2014

Ing. Janka Levická
vedúca certifikačného orgánu
certifikujúceho výrobky
Head of Product Certification Body

DECLARATION OF CONFORMITY

issued

according to § 13 par. 1 of Act no. 264/99 Coll. on technical requirements for products and on conformity assessment as amended by later regulations and government regulations no. 194/2005 Coll., which sets the technical requirements for electromagnetic compatibility of equipment and no. 308/2004 Coll. as amended by Government Decree no. 318/2007 Coll., which sets technical requirements for electrical equipment.

The declaration of conformity is issued by:

Business name:	**KOVO, s.r.o.**
Registered seat:	**Družby 77, 921 01 Piešťany - Kocurice**
Business ID:	**31 444 512**

As the manufacturer:

Name:	**wafer-maker**
Type:	**OB - 1**
Country of origin:	**Slovakia**

Product description and function: The wafer-maker is an electric device designed for the home production (baking) of individual types of wafers.

The manufacturer declares that:

A. The product in question is safe for the intended use and measures are taken to ensure that all products placed on the market comply with the technical documentation, with the essential requirements of the government regulations applicable to them and with the requirements of the technical regulations referred to in point B.

B. The properties of this product meet the technical requirements applicable to this product, which are specified in the relevant government regulations, or in other / other / - technical regulations.

C. Conformity assessment was completed with the issuing of CERTIFICATE OF CONFORMITY no. 141299001 according to: government regulation no. 194/2005 Coll. on electromagnetic compatibility of equipment, government regulation no. 308/2004 Coll. as amended by Government Decree no. 318/2007 Coll. on electrical equipment.

D. The following were used in the conformity assessment:

- harmonized technical standards: STN EN 60335-2-9: 2004-08.

In Piešťany on 14.01.2014

ADVICE AND TIPS FOR BAKING WAFERS

Don't despair :)

If the wafers fail to bake to your liking, there may be several reasons. In the lines that follow, we offer you a few tips and tricks on how to proceed with the preparation of the batter and the baking itself.

o For the **very first baking**, the baking trays must be “baked out”. We recommend starting with baking salty wafers. The batter for salty wafers does not contain **sugar, which caramelizes**, so during the first baking it can cause the wafers to stick to the baking trays. By baking a salty batter, the trays are “baked out” and are then ready for further baking. The first 10 baked wafers must be discarded - DO NOT EAT!

o **Baking temperature - baking time - wafer thickness** are all related: if the temperature is too high, the surface of the wafer may be overdone, but moisture will remain closed inside the wafer (the water from the wafer will have nowhere to escape). Shorter baking times are best achieved when baking thinner wafers - increasing wafer thickness, means that the baking time will also increase.

o A thicker wafer is suitable for salty wafers and tubes, thinner ones are best for classic Christmas wafers.

o **The most important ingredient in the batter is the flour,** which will determine how successful the baking will be. Use only quality flour. Sometimes it is necessary to try several types of flour until you achieve the perfectly baked wafer. For beginners, we recommend using EXTRA SPECIAL flour. We have been very satisfied with the brand - Pohronský Ruskov.

o **Do not use too much sugar**, it causes the wafers to stick to the trays.

o **Give priority to crystal sugar** over powdered sugar (powdered sugar also contains added anti-caking agents that cause batter to stick).

o As a result of certain **specific ingredients in the batter** (nuts, dried fruit, fruit acids, ...) the batter can stick. In this case, reduce the amount of these raw materials.

o The most suitable fat for making batter is **butter.**

o The batter should be at **room temperature** so as not to lower the temperature of the baking trays too much. You can preheat ingredients from the fridge such as milk and butter in advance.

o Thoroughly mix the wafer batter. **Stir the batter** regularly during baking.

o **Cheese** in the wafer batter - use quality hard cheeses with a fat content in the dry matter of at least 45%.

o To keep the wafers **fresh for a long time**, store them in an air-tight resealable container or bag (so that they do not get damp).

Recepies for making the wafer batter

For testing and adjusting the batter, we recommend making a smaller amount, e.g. half a batch.

Abbreviations: tsp. – teaspoon, Tbsp. – tablespoon

Classic sweet Christmas wafers

1000 ml milk (fresh, whole milk not long-lasting)

1000 g flour (smooth special)

170 sugar (preferably crystal sugar as powdered sugar contains starch)

600 ml water

1 whole egg

1 pack of vanilla sugar (10 g)

65 g melted butter

Instructions:

Heat the milk and water to a lukewarm temperature, add sugar, butter, vanilla and let them dissolve. Then add the whole egg and mix well. Finally, gradually add the flour and whisk until smooth. If the dough is thick, add 150 ml - 200 ml of water. Thoroughly mix and then pour the batter lengthwise into the middle of the baking tray with a spoon (we recommend using a wooden one that is deeper).

Sweet tubes

1200 ml milk

600 g flour (smooth special)

300 g crystal sugar

2 egg yolks

1 pack of vanilla sugar (10 g)

2 tsp. melted butter

Instructions:

Heat the milk and water to a lukewarm temperature, add sugar, butter, vanilla and let them dissolve. Then add the egg yolks and mix well. Finally, gradually add the flour and whisk until smooth. If the batter is thick, add 150 ml - 200 ml of water. Thoroughly mix and pour the batter lengthwise into the middle of the baking tray with a spoon (we recommend using a large wooden spoon, which is deeper). After partial evaporation of any excess water from the batter, open the wafer-maker and carefully, while the wafer is still moist and on the tray, use a baton to roll it into a tube.

Salty wafers

1000 ml milk

600 g smooth flour

2 egg yolks

4 Tbsp. butter

3 tsp. salt

ground caraway seed

Instructions:

Heat the milk to a lukewarm temperature, add butter, egg yolks, salt and caraway. Finally, gradually add the flour and whisk until smooth. If the batter is thick, add 150 ml - 200 ml of water. Mix thoroughly and pour the batter for two small round wafers. We recommend using a wooden spoon, which is deeper , which makes pouring the batter easier.

We wish you MUCH SUCCESS with the baking and BON APETIT with the munching!!

Your Wafee team :)

Your notes: